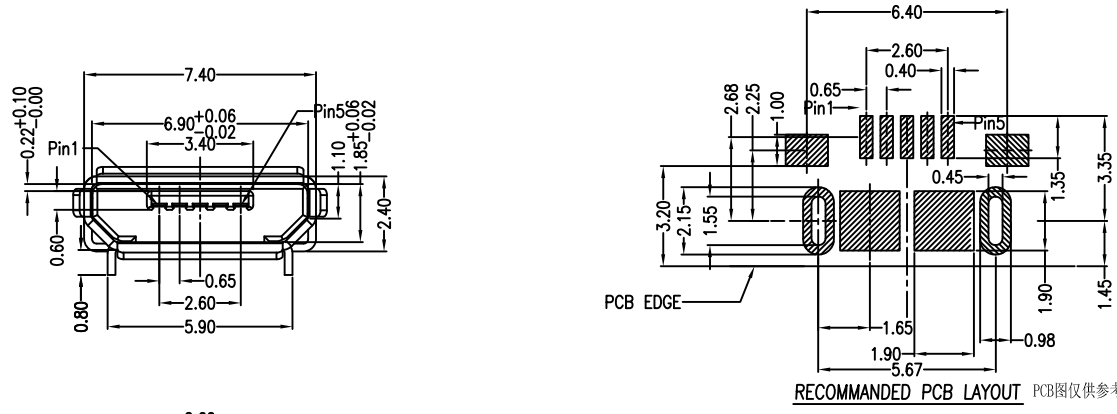
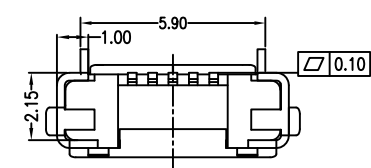
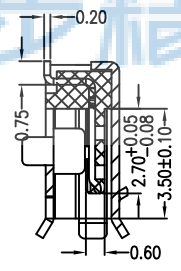
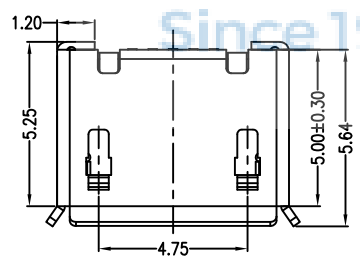
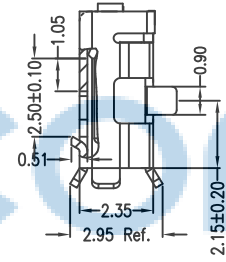
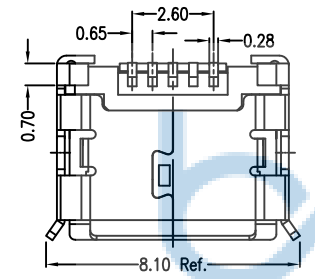


REV.	ECN NO.	CONTENT	DATE	ENGINEER
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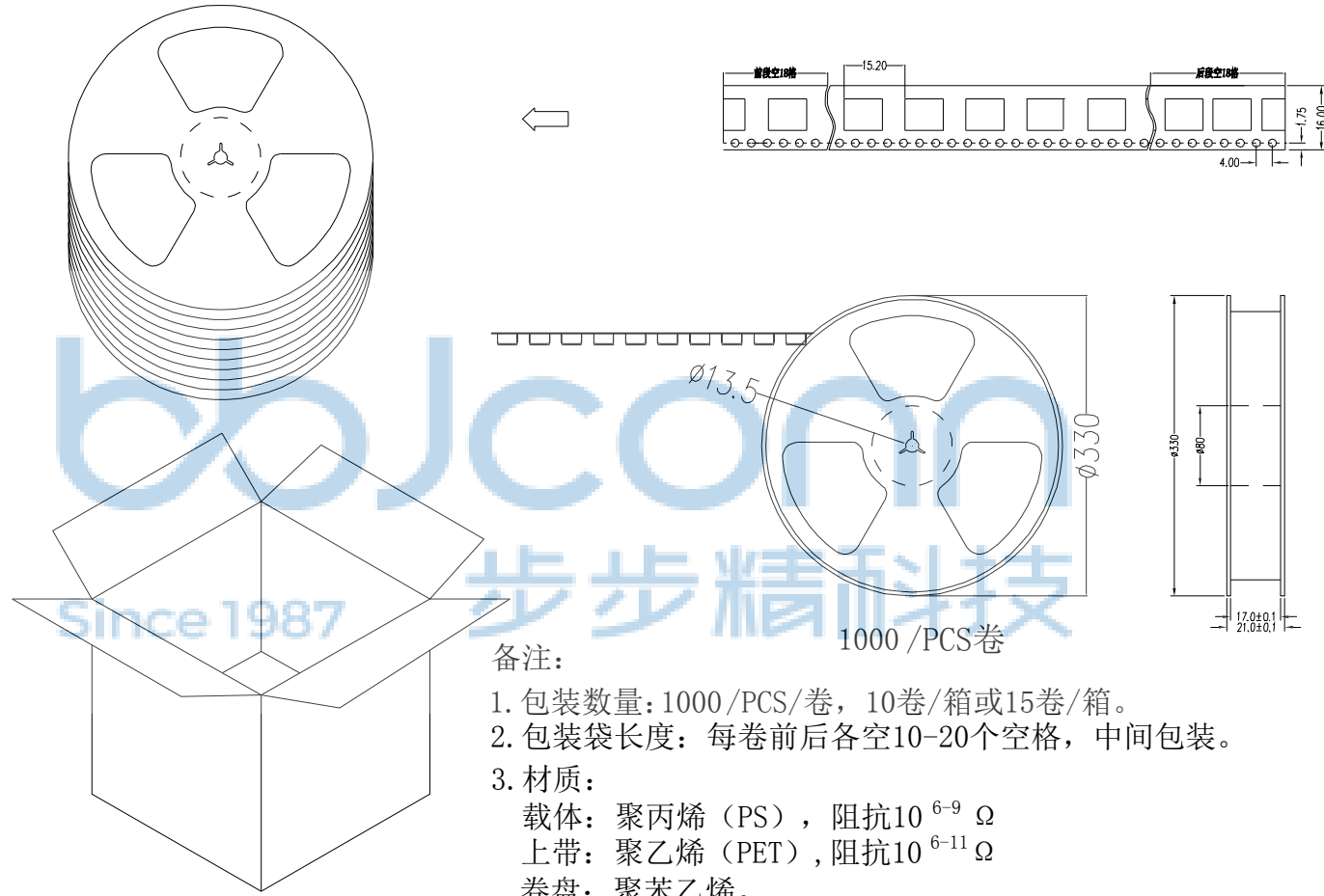


- Note:
- Material:
 - Housing: High temperature thermoplastic with g.f, UL94v-0
 - Contact: copper alloy, $t=0.20\text{mm}$ contact area Au flash planting;
 - Shell: copper or SUS304, $t=0.25\text{mm}$ Sn planting 60U" min.
 - Specification:
 - Current rating: 1, 5PIN 1.8A Max/2, 3, 4PIN 1A Max.
 - Dielectric withstanding voltage: 100 V(ac) for 1 min.
 - Contact resistance: 30 mΩ Max.
 - Insulation resistance: 100 MΩ Min.
 - Total mating force: 3.57 Kgf Max.
 - Total unmating force: 1.0 Kgf Min.
 - Temperature range: $-30^{\circ}\text{C} \sim 80^{\circ}\text{C}$
 - Solderability: 90% area min;



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PDWG.NO: 0113-1		PJ. NO.: MC.01.21-21-1004 SIZE: A4 DRW NO.: FINISH: SEE NOTES MAT'L.: SEE NOTES SCALE: N/A REV.: A3 UNIT: mm PAGE: 1/1			

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0			2023 20/04	



备注:

1. 包装数量: 1000 /PCS/卷, 10卷/箱或15卷/箱。
2. 包装袋长度: 每卷前后各空10-20个空格, 中间包装。
3. 材质:
载体: 聚丙烯 (PS), 阻抗 $10^{6-9} \Omega$
上带: 聚乙烯 (PET), 阻抗 $10^{6-11} \Omega$
卷盘: 聚苯乙烯。

纸箱规格: 345*345*23MM
纸箱规格: 345*345*35MM



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APPD.	JM_Zheng	23/05'02	PJ. NO.: MC.01.21-21-1004 SIZE: A4 DRW NO.:		
CHKD.	LYX	23/05'02	FINISH: SEE NOTES MAT'L.: SEE NOTES SCALE: N/A REV.: A3 UNIT: mm PAGE: 1/1		
PDWG.NO:	0113-1	DR.	SGF	23/05'02	